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## INFORMATION DISCLOSURE CITATION

PTO-1449

ATTY. DOCKET NO. P118-US
P118-US

SERIAL NO. 10/666,671

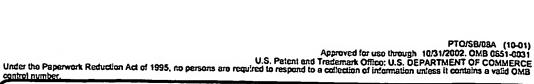
APPLICANT Shi, et al.

SHEET I OF 1 FILING DATE 9/17/03

GROUP Not Yet Assigned

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		U.S. P.	ATENT DOCUMENT	<u>s</u>			
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING	G DATE
LV	6,558,559	05-2003	Becker, et al.				
LV	2004-0165250	08-2004	Aubuchon				
LV	2003-0080082	05-2003	Chinn, et al.				
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		FOREIG	N PATENT DOCUMEN	TS			
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS		LATION
INTIALS						YES	NO
	OTHER DOC	UMENTS (Incl	uding Author, Title, Date	e, Pertinent	Pages, Etc.)		
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EXAMINER	/Lan V	inh/	DATE CONSIDERED		05/29/2006	,	

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Complete if Known Substitute for form 1449A/PTO **Application Number** 10/666,671 **INFORMATION DISCLOSURE** Filing Date 9/17/03 STATEMENT BY APPLICANT First Named Inventor Shi Art Unit 1765 (use as many sheets as necessary) Examiner Name Not Yet Assigned Sheet of Attorney Docket Number P118-US

			U.S. PAT	ENT DOCUMENTS	
Examiner Initials		<u> Document Number</u> Number - Kind Code <sup>2</sup> (if known	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
ΓΛ	AA	US- 3.511.727	05-12-1970	Hays, R.G.	. ,да: оо хэрэсц
	AB	US. 4,190,488	02-26-1980	Winters, H.F.	
	AC	US- 4.310,380	12-12-1982	Flamm et al.	
- 1	AD	US- 4.498,953	02-12-1985	Cook et al.	
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	No. 1	Country Code 3 -Number 4 - Kind Code 9 (# known)	Publication Date MM-DD-YYYY	Applicant of Cited Document	Where Relevant Passages or Relevant Figures Appear	7	
LV	ВА	EP-0704884-A2	04-03-1996	Mehta, J.		Т	
	88	EP-0822582-A2	02-04-1998	Bhardwai, J.K.			
	ВС	EP-0822584-A2	04-04-1998	Bhardwai, J.K.			
	BD	EP-0838839-A2	04-29-1998	Bhardwai, J.K.			
	BE	EP-0878824-A2	11-18-1998	McQuarrie et al.			
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11	ВН	WO-98/05605	02-12-1998	Bhardwal, J.K.			
V	81	WO-98/13856	04-02-1998	Bhardwai, J.K.	İ		
LA	BJ	WO-98/32163	07-23-1998	Tai et al.			

Examiner	/Lan Vinh/	Date	05/29/2006
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3 Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). 
4 For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. 
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Substitute for form 1449A/PTO

## INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet of

Complete if Known				
Application Number 10/666,671				
Filing Date	9/17/03			
First Named Inventor	Shi			
Art Unit	1765			
Examiner Name	Not Yet Assigned			
Attorney Docket Number	P118-US			

			U.S. PAT	ENT DOCUMENTS	
Examiner Initials		Document Number Number - Kind Code <sup>1</sup> (if known	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
LV	AU	US- 6.051,503	04-18-2000	Bhardwai, J.K.	
ТΛ	AV	US. 6.162,367	12-19-2000	Teietet.	İ
	AW	US- 6,277,173 B1	08-21-2001	Sadakata et al.	1
	AX	US- 6,290,884 B1	09-18-2001	Patel et al.	İ
- 1	AY	US. 6,328,801 B1	12-11-2001	Gary et al.	İ
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	AAB	US- 2001/0002663 A1	06-07-2001	Tai et al.	r
	AAC	US- 2002/0033229 A1	03-21-2002	Lebouitz et al.	İ
1		US- 2003/0054588	03-20-2003	Patel, et al.	Ì
	1	US- 2002/0185699	12-12-2002	Reid	
	i	US- 2002/0121502	09-15-2002	Patel, et al.	Ì
	1	US- 2002/0047172	04-25-2002	Reid	<b>!</b>
		US- 6,436,229	08-20-2002	Tai, et al.	
	İ	us-			
	ĺ	US- 2002/0196524	12-26-2002	Huibers, et al.	1
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11/	İ	US- 6,409,876	6-25-2002	McQuarrie, et al.	
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Examiner	Cito	Foreign Patent Document	D. blacker Dete	Name of Patentee or	Pages, Columns, Lines,	
	No.1	Country Code 3 -Number 4 - Kind Code 5 (# known)	Publication Date MM-DD-YYYY	Applicant of Cited Document	Where Relevant Passages or Relevant Figures Appear	Te
LV	ВК	WO-99/01887	01-14-1999	Lea et al.		
1	BL	WO-99/03313	01-21-1999	Lea et al.		İ
	ВМ	WO-99/49506	09-30-1999	McQuarrie, A.D.		İ
	BN	WO-00/52740	08-08-2000	Bhardwai et al.		İ
	во	JP-1982/57098679-A	06-18-1982	Tsunetoshi, A.		1
	BP	JP-1983/58130529-A	08-04-1983	Yoshihiro et al.		1
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	BR	JP-1986/61053732-A	03-17-1986	Arata et al.		1
V	BŞ	JP-1986/61134019-A	06-21-1986	Shinji et al.		İ
T.V	ВТ	JP-1986/61181131-A	08-13-1986	Shinii et al.		

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Substitute for form 1449A/PTO Complete if Known **Application Number** 10/666,671 INFORMATION DISCLOSURE 9/17/03 Filing Date STATEMENT BY APPLICANT First Named Inventor Shi Art Unit 1765 (use as many sheets as necessary) **Examiner Name** Not Yet Assigned Sheet of Attorney Docket Number P118-US

<del></del>		U.S. PAT	ENT DOCUMENTS	-
Examiner Cite Initials No.1	Document Number Number - Kind Code <sup>2</sup> (if known	Publication Date	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
TA TA	US- 6.238.581 US- 6.115.172 US- 6.204.080 US- 2003/0071015 US- 2002/0164879 US- 2003/0077878 US- 6.197.610 US- 6.500.356 US- 2003/0124848 US- 2003/0124848 US- 2003/0219986 US- 4.551.197 US- 2004/0069747 US- 2002/0195423 US- 2002/0195423 US- 2002/0163051 US- US- US-	5-29-2001 9-5-2000 3-20-2001 4-17-2003 11/07/02 4-24-2003 3-6-2001 12-31-2002 7-3-2003 11-27-2003 11-5-1985 4-15-2004 12-26-2002 2-26-2004 11-17-02	Hawkins, et al. Jeono Hwano Chinn, et al. Leung, et al. Kumar Toda Goto, et al. Chinn, et al. Ratiner Gullmette Patel, et al. Patel, et al. Doan, et al. Gopal	rigures Appear

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Examiner	Foreign Patent Document			Name of Patentes or	Pages, Columns, Lines,	Г			
Initials	No.1	Country Code 3 - Number 4 - Kind Code 6 (# known)	Publication Date MM-DD-YYYY	Applicant of Cited Document	Where Relevant Passages or Relevant Figures Appear	+			
LV	BU	JP-1986/61187238-A	08-20-1986	Nobuo et al.		H			
	BV	JP-1986/61270830-A	12-01-1986	Toru, T.		l			
- 1	вw	JP-1987/62071217-A	04-01-1987	Toru et al.		l			
	ВХ	JP-1988/63155713-A	06-28-1988	Tadashi, F.		ŀ			
	BY	JP-1989/01208834-A	08-22-1989	Nobuo et al.		ľ			
	BZ	JP-1989/10217921-A	08-31-1989	Tsuneo et al.					
	CA	JP-1990/02250323-A	10-08-1990	Susumu et al.					
11	СВ	JP-1991/03012921-A	01-21-1991	Nobuo et al.					
V	CC	JP-1992/04096222-A	03-27-1992	Atsuyuki, A.					
L.V	CD	JP-1995/07029823-A	01-31-1995	Hiroshi, T.					

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			U.S. PATI	NT DOCUMENTS	
Examiner	Cita	Document Number	Publication Date	Name of Patentee or	Pages, Columns, Lines, Where
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LV	CE	JP-1997/09251981-A	09-22-1997	Kazuaki et al.		l
LV	CF	JP-1998/10313128-A	11-24-1998	Hanmin et al.		
LV	CG	JP-1998/10317169-A	12-02-1998	McQuarrie et al.		
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	ubstitute for form 1449B/PTO NFORMATION DISCLOSURE TATEMENT BY APPLICANT	OL COURT	Application Number	10/666.671			
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	(use as many sh	reets a	s necessary)	Examiner Name	Not Yet Assigned		
Sheet	5	of	10	Attorney Docket Number	P118-US		

Examiner Initials	Cite No. 1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	
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	DC	HABUKA et al., "Dominant Overall Chemical Reaction in a Chlorine Trifluoride-Silicon-Nitrogen System at Atmospheric Pressure", Japan Journal of Applied Physics Vol. 38 (1999), pp. 6466-6469.	
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	DE	HOULE, F.A., "Dynamics of SiF4 Description During Etching of Silicon by XeF2", IBM Almaden Research Center (April 15, 1987), pp. 1866-1872.	
	DF	FLAMM et al., "XeF2 and F-Atom Reactions with Si: Their Significance for Plasma Etching", Solid State Technol. 26, 117 (1983).	
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Substitute for	STATEMENT BY APPLICANT  Filling Date First Name Group Art I	Co	Complete if Known		
	FORMATION DISCLOSURE		OL COURT	Application Number	10/666.671
INFOR	KMAHON	DIS	CLUSURE	Filing Date	9/17/03
ISTATI	EMENT R	ΥΔ	PPI ICANT	First Named Inventor	Shi
10.7			LIOAN	Group Art Unit	1765
	(use as many shi	eets a	s necessary)	Examiner Name	Not Yet Assigned
Sheet	6	of	10	Attorney Docket Number	P118-US

Examiner Initials	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the ltem (book, magazine, journal, serial, symposium, catalog, etc.), date, paga(s), volume-issue number(s), publisher, city and/or country where published	1
LV	DL	WINTERS, H.F., "Etch Products from the Reaction of XeF2 with SiO2, SiO3, Si3N4, SiC, and Si in the Presence of Ion Bombardment", J. Vac. Sci. Technol. B 1(4) (Oct/Dec 1983), pp. 927-931.	
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	DN	XACTIX, Inc., Marketing Brochure (June 27, 1999).	
	000	"Xenon Diffuoride Isotropic Etch System: Seeing is Believing", Surface Technology Systems Ltd. brochure, Newport, UK (date unknown).	
	DP	Assorted promotional literature, Surface Technology Systems Ltd., Newport, UK (July 28, 1999).	
V LV		Kurt Williams, Etch Rates for Micromachining Processing-Part II, 2003 IEEE, Pgs 761-778, Journal of Microelectromechanical Systems, Vol. 12, No. 6, December 2003.	
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Signature		Considered	

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LV	ВА	ANDERSON, H.M., "Plasma Diagnostics for Semicondicutor Processing", 2000 Digest of the LEOS Topical Meetings (July 24 - 28, 2000), pp. 117-118 (abstract only).	
4	88	BARYSHEV et al., "Monitoring of XiO2/Si Plasma Etching and End-Point Detection", Mikroetektronika (Russia), Vol. 25, No. 5 (Sept/Oct 1996), pp. 373-379 (abstract only).	
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Examiner	/Lan Vinh/	Date	05/29/2006
Signature		Considered	

<sup>&</sup>quot;EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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Complete if Known Substitute for form 1449B/PTO 10/658,671 **Application Number** INFORMATION DISCLOSURE 9/17/03 Filing Date STATEMENT BY APPLICANT First Named Inventor Shi **Group Art Unit** 1765 Not Yet Assigned Examiner Name (use as many sheets as necessary) P118-US Attorney Docket Number of Sheet

Examiner Initials	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	
ΓΛ	BL	LI et al., "Mass Spectomatric Measurements on Inductively Coupled Fluorocarbon Plasmas: Positive lons, Radicals and Endpoint Detection", J. Vac. Sci. Technol. A, Vac. Surf. Films, Vol. 17, No. 5 (Sept. 1997), pp. 2438-2446 (abstract only).	
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ı	Examiner	/Lan Vinh/	Date	05/29/2006
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Substitute	or form 1449B/PTC	,		Complete if Known		
INFORMATION DISCLOSURE				Application Number	10/666,671	
INFOR	RMATION	DIS	CLOSURE	Filing Date	9/17/03	
STAT	EMENT P	Y A	PPLICANT	First Named Inventor	Shi	
JIAI		,,,	LIOAN	Group Art Unit	1765	
(use as many sheets as necessary)				Examiner Name	Not Yet Assigned	
Sheet	9	of	10	Attorney Docket Number	P118-US	

Examiner Initials No. 1		Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where nublished.			
		SEBEL et al., "Reaction Layer Dynamics in Ion-Assisted Si/XeF2 Etching: Temperature Dependence", J. Vac. Sci. Technol. A, Vac. Surf. Films, Vol. 18, No. 6, (Nov. 2000), pp. 2759-2769 (abstract only).			
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	СВ	TODA et al., "Thin Beam Bulk Micromachining Based on RIE and Xenon Difluoride Silicon Etching", International Solld State Sensors and Actuators Conference (Transducers '97), Chicago, IL, Vol. 1 (June 16 - 19, 1997), pp. 671-674.			
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STAT	EMENT F	ΣΥ ΔΙ	PPLICANT	First Named Inventor	Shi	
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LV	СН	WARNEKE, et al., "In Situ Characterization of CMOS Post-Process Micromachining", Sens. Actuators A, Phys. (Switzerland), Vol. A89, No. 1-2 (March 20, 2001), pp. 142-151 (abstract only).	
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	З	WODECKI, N.D., Low Open Area Multi-Layered Dielectric Film Etch Endpoint Detection Using EndPoint Plus (TM)", Proceedings of the SPIE - The International Society for Optical Engineering, Vol. 3882 (1999), pp. 231-238 (abstract only).	
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$V_{rv}$	CL	YUE et al., "Plasma Etching Endpoint Detection Using Multiple Wavelengths for Small Open Area Wafers", J. Vac. Sci. Technol. A, Vac. Surf. Films, Vol. 19, No. 1 (Jan. 2001), pp. 66-75 (abstract only).	

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